SCLS325G - MARCH 1996 - REVISED JULY 2003

- Wide Operating Voltage Range of 2 V to 6 V
- Typical Switch Enable Time of 18 ns
- Low Power Consumption, 20-µA Max I_{CC}
- Low Input Current of 1 μA Max
- High Degree of Linearity
- High On-Off Output-Voltage Ratio
- Low Crosstalk Between Switches
- Low On-State Impedance . . . 50-Ω TYP at V_{CC} = 6 V
- Individual Switch Controls

description/ordering information

The SN74HC4066 is a silicon-gate CMOS quadruple analog switch designed to handle both analog and digital signals. Each switch permits signals with amplitudes of up to 6 V (peak) to be transmitted in either direction.

Each switch section has its own enable input control (C). A high-level voltage applied to C turns on the associated switch section.

Applications include signal gating, chopping, modulation or demodulation (modem), and signal multiplexing for analog-to-digital and digital-to-analog conversion systems.

TA	PACK	AGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING					
	PDIP – N	Tube of 25	SN74HC4066N	SN74HC4066N					
		Tube of 50	SN74HC4066D						
	SOIC – D	Reel of 2500	SN74HC4066DR	HC4066					
		Reel of 250	SN74HC4066DT						
–40°C to 85°C	SOP – NS	Reel of 2000	SN74HC4066NSR	HC4066					
	SSOP – DB	Reel of 2000	SN74HC4066DBR	HC4066					
		Tube of 90	SN74HC4066PW						
	TSSOP – PW	Reel of 2000	SN74HC4066PWR	HC4066					
		Reel of 250	SN74HC4066PWT						

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each switch)

INPUT CONTROL (C)	SWITCH
L	OFF
н	ON



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



DB, N, NS, OR PW PACKAGE (TOP VIEW)							
1A 1B 2B 2A 2C 3C GND	[2] [3]	14 13 12 11 10 9 8] V _{CC}] 1C] 4C] 4A] 4B] 3B] 3A				

D,

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logic diagram, each switch (positive logic)



One of Four Switches

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC} (see Note 1)		-0.5 V to 7 V
Control-input diode current, I_{I} (V_{I} < 0 or V_{I} > V_{C}	сс)	±20 mA
I/O port diode current, I _I (V _I < 0 or V _{I/O} > V _{CC})		±20 mA
On-state switch current ($V_{I/O} = 0$ to V_{CC})		±25 mA
Continuous current through V _{CC} or GND		±50 mA
Package thermal impedance, θ_{JA} (see Note 2):	D package	86°C/W
	DB package	96°C/W
	N package	80°C/W
	NS package	76°C/W
	PW package	113°C/W
Storage temperature range, T _{stg}		5°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages are with respect to ground unless otherwise specified.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 3)

			MIN	NOM	MAX	UNIT	
VCC	Supply voltage	2†	5	6	V		
V _{I/O}	VI/O I/O port voltage				VCC	V	
		$V_{CC} = 2 V$	1.5		VCC		
VIH		$V_{CC} = 4.5 V$	3.15		VCC	V	
		V _{CC} = 6 V	4.2		VCC		
		$V_{CC} = 2 V$	0		0.3		
VIL	Low-level input voltage, control inputs	$V_{CC} = 4.5 V$	0		0.9	V	
		$V_{CC} = 6 V$	0		1.2		
		$V_{CC} = 2 V$			1000		
$\Delta t/\Delta v$	Input transition rise/fall time	$V_{CC} = 4.5 V$			500	ns	
		V _{CC} = 6 V			400		
Τ _Α	Operating free-air temperature		-40		85	°C	

[†] With supply voltages at or near 2 V, the analog switch on-state resistance becomes very nonlinear. It is recommended that only digital signals be transmitted at these low supply voltages.

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	TEST CONDITIONS		∖ = 25° Ω	;	MIN MAX	UNIT	
	FANAMETER		TEST CONDITIONS	Vcc	MIN	TYP	MAX		UNIT
				2 V		150			
ron	On-state switch resista	ance	$I_T = -1 \text{ mA}, V_I = 0 \text{ to } V_{CC},$ $V_C = V_{IH} \text{ (see Figure 1)}$	4.5 V		50	85	106	Ω
				6 V		30			
				2 V		320			
ron(p)	ron(p) Peak on-state resistance		$V_I = V_{CC}$ or GND, $V_C = V_{IH}$, $I_T = -1$ mA	4.5 V		70	170	215	Ω
				6 V		50			
Ц	Control input current		$V_{C} = 0 \text{ or } V_{CC}$	6 V		±0.1	±100	±1000	nA
Isoff	Off-state switch leakage current		$V_I = V_{CC}$ or 0, $V_O = V_{CC}$ or 0, $V_C = V_{IL}$ (see Figure 2)	6 V			±0.1	±5	μA
I _{son}	on On-state switch leakage current		$V_I = V_{CC}$ or 0, $V_C = V_{IH}$ (see Figure 3)	6 V			±0.1	±5	μA
ICC	Supply current		$V_{I} = 0 \text{ or } V_{CC}, \qquad I_{O} = 0$	6 V			2	20	μA
C.		A or B		5 V		9			۶E
Ci	Input capacitance	С		57		3	10	10	pF
Cf	Feed-through capacitance	A to B	$V_{I} = 0$			0.5			pF
Co	Output capacitance	A or B		5 V		9			pF



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switching characteristics over recommended operating free-air temperature range

	RAMETER	FROM			Vaa	Тд	_= 25°C	;	MIN MAX	UNIT					
FA	RAMETER	(INPUT)	(OUTPUT)	CONDITIONS	Vcc	MIN	TYP	MAX	WIIN	IVIAA	UNIT				
	.						10	60		75					
^t PLH [,] ^t PHL	Propagation delay time	A or B	B or A	C _L = 50 pF (see Figure 4)	4.5 V		4	12		15	ns				
*FIIL				(000 1 iguro i)	6 V		3	10		13					
4	Quitab			$R_{L} = 1 k\Omega,$	2 V		70	180		225					
^t PZH [,] ^t PZL	Switch turn-on time	С	A or B	C_ = 50 pF	4.5 V		21	36		45	ns				
ΤZL				(see Figure 5)	6 V		18	31		38					
	Quitab	с	A or B	$R_{L} = 1 k\Omega,$	2 V		50	200		250					
^t PLZ [,] tPHZ	Switch turn-off time			$C_{L} = 50 pF$	4.5 V		25	40		50	ns				
1112				(see Figure 5) 6 V			22	34		43					
	Control			$C_{L} = 15 \text{ pF},$ $R_{I} = 1 k\Omega,$	2 V		15								
fı	input	С	A or B	A or B	A or B	A or B	A or B	A or B $V_{C} = V_{CC}$ or GND,	4.5 V		30				MHz
	frequency			V _O = V _{CC} /2 (see Figure 6)	6 V		30								
	Control feed-through	С	A or B	$C_L = 50 \text{ pF},$ $R_{in} = R_L = 600 \Omega,$ $V_C = V_{CC} \text{ or GND},$	4.5 V		15				mV				
	noise	0	AUR	$f_{in} = 1 \text{ MHz}$ (see Figure 7)	6 V		20				(rms)				

operating characteristics, V_{CC} = 4.5 V, T_A = 25°C

	PARAMETER	TEST C	TYP	UNIT	
Cpd	Power dissipation capacitance per gate	C _L = 50 pF,	f = 1 MHz	45	pF
	Minimum through bandwidth, A to B or B to A [†] [20 log (V _O /V _I)] = -3 dB	$C_L = 50 \text{ pF},$ $V_C = V_{CC}$	RL = 600 Ω, (see Figure 8)	30	MHz
	Crosstalk between any switches [‡]	C _L = 10 pF, f _{in} = 1 MHz	R _L = 50 Ω, (see Figure 9)	45	dB
	Feed through, switch off, A to B or B to A^{\ddagger}	C _L = 50 pF, f _{in} = 1 MHz	R _L = 600 Ω, (see Figure 10)	42	dB
	Amplitude distortion rate, A to B or B to A	C _L = 50 pF, f _{in} = 1 kHz	R _L = 10 kΩ, (see Figure 11)	0.05%	

[†] Adjust the input amplitude for output = 0 dBm at f = 1 MHz. Input signal must be a sine wave.

[‡]Adjust the input amplitude for input = 0 dBm at f = 1 MHz. Input signal must be a sine wave.



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Figure 4. Propagation Delay Time, Signal Input to Signal Output



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Figure 5. Switching Time (t_{PZL} , t_{PLZ} , t_{PZH} , t_{PHZ}), Control to Signal Output



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Figure 6. Control-Input Frequency



Figure 7. Control Feed-Through Noise



Figure 8. Minimum Through Bandwidth



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Figure 10. Feed Through, Switch Off



Figure 11. Amplitude-Distortion Rate



8-Jun-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74HC4066D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HC4066DBLE	OBSOLETE	SSOP	DB	14		TBD	Call TI	Call TI
SN74HC4066DBR	ACTIVE	SSOP	DB	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HC4066DBRE4	ACTIVE	SSOP	DB	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HC4066DE4	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HC4066DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HC4066DRE4	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HC4066DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4066DT	ACTIVE	SOIC	D	14	250	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HC4066DTE4	ACTIVE	SOIC	D	14	250	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HC4066N	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74HC4066NE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74HC4066NSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HC4066NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4066PW	ACTIVE	TSSOP	PW	14	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HC4066PWE4	ACTIVE	TSSOP	PW	14	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HC4066PWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI
SN74HC4066PWR	ACTIVE	TSSOP	PW	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HC4066PWT	ACTIVE	TSSOP	PW	14	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HC4066PWTE4	ACTIVE	TSSOP	PW	14	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements





for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012 variation AB.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



MECHANICAL DATA

MSSO002E - JANUARY 1995 - REVISED DECEMBER 2001

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-150



MECHANICAL DATA

MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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